

67,200-409; TSMC 00-661  
Serial Number 09/978,420

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**TO:** Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**FROM:** Tung & Associates  
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Bloomfield Hills, MI 48302

**DATE:** 7 July 2004

**REF:** Applicant : Chou et al Filing Date : 15 October 2001  
Serial No. : 09/978,420 Atty No. : 67,200-409; TSMC 00-661  
Art Unit : 2815 Examiner : N. Drew Richards  
Title : Microelectronic Fabrication With Upper Lying Aluminum Fuse  
Layer in Copper Interconnect Semiconductor Technology and  
Method for Fabrication Thereof

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**RESPONSE TO OFFICE ACTION MADE FINAL**

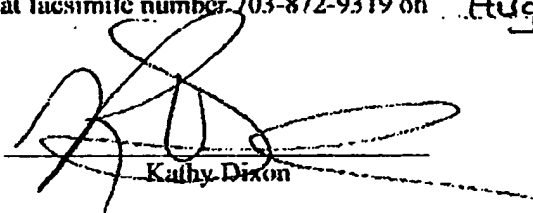
Sir:

In response to an office action mailed on 8 June 2004 and made FINAL, please consider the following remarks pertaining to the above referenced application.

There are no amendments to the specification, claims or drawings. A Listing of the Claims begins on page 2 of this paper. Remarks begin on page 4 of this paper.

**CERTIFICATE OF FACSIMILE TRANSMISSION**

I hereby certify that this correspondence is being facsimile transmitted to the United States Patent and Trademark Office at facsimile number 703-872-9319 on Aug. 9, 2004.

  
Kathy Dixon